

**VLSI SOLUTION 0Y - VS1011E-S/LSR-ROHS - SOIC28 300MILS - document A Revision: 2.0**

**Marking on device: VS1011E R**

**XXXXXXXXXXXX YYWW where YYWW = assembly Year and Week > 0904**

Component	Weight (mg)	Type	Material	CAS#	%	Weight (mg)
Chip	19.617		Silicon	7440-21-3	100.00	19.617
Lead Frame	256.468	A194	Copper	7440-50-8	97.94	249.189
			Fe	7439-89-6	2.00	5.089
			P	7723-14-0	0.02	0.038
			Zn	7440-66-6	0.05	0.127
		Ag	Silver	7440-22-4	100.00	2.024
Mold Compound	529.866	SUMIKON EMEG600	Silica Fused	60676-86-0	87.70	464.693
			Epoxy Resin	Trade Secret	5.00	26.493
			Phenol Resin	Trade Secret	5.00	26.493
			Carbon Black	1333-86-4	0.30	1.590
			Epoxy, Cresol Novolac	29690-82-2	2.00	10.597
Bonding Wire	1.113	Wire Dia : 1 mils	Au	7440-57-5	99.99	1.113
			Dopant	-	0.01	0.000
Epoxy	1.550	CRM 1076NS	Silver (Ag)	7440-22-4	82.00	1.271
			Epoxy Resin	9003-36-5	10.00	0.155
			Diluent	Trade Secret	2.00	0.031
			Dicyandiamide	461-58-5	0.90	0.014
			Hardener	Trade Secret	5.10	0.079
Plating	6.867	LEAD FREE SOLDER Sn100%	Sn	7440-31-5	99.987	6.866
			Pb	7439-92-1	0.005	0.000
			Cu	7440-50-8	0.003	0.000
			Cd	7440-43-9	0.001	0.000
			Bi	7440-69-9	0.003	0.000
			Sb	7440-36-0	0.001	0.000
Total Weight	815.481					815.481